



Semiconductor Device Type: Q9C LFBGA-256-14x14x1.56mm-SAC105						Package Homogeneous Materials				
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	15.94	(mg) Total	Die	% of Total Weight	2.68
Silicon	7440-21-3	Die	2.68	15.94	26827		Silicon	7440-21-3	100.00	
Epoxy Resin A	Trade Secret	Mold Compound	1.32	7.82	13166		Total 100.00			
Epoxy Resin B	Trade Secret	Mold Compound	1.32	7.82	13166					
Phenol Resin	Trade Secret	Mold Compound	1.32	7.82	13166	260.72	(mg) Total	Mold Compound	% of Total Weight	43.89
Silica, vitreous	60676-86-0	Mold Compound	31.82	189.02	318187		Epoxy Resin A	Trade Secret	3.00	
Silicon dioxide	7631-86-9	Mold Compound	6.58	39.11	65832		Epoxy Resin B	Trade Secret	3.00	
Aluminium and its compounds	Trade Secret	Mold Compound	1.32	7.82	13166		Phenol Resin	Trade Secret	3.00	
Carbon Black	1333-86-4	Mold Compound	0.22	1.30	2194		Silica, vitreous	60676-86-0	72.50	
Glass, oxide	65997-17-3	PCB	2.96	17.60	29628		Silicon dioxide	7631-86-9	15.00	
Aluminium hydroxide oxide	24623-77-6	PCB	1.43	8.51	14319		Aluminium and its compounds	Trade Secret	3.00	
Bismaleimide-Triazine resin	Trade Secret	PCB	1.00	5.96	10030		Carbon Black	1333-86-4	0.50	
Epoxy resin	Trade Secret	PCB	0.67	4.00	6731	Total 100.00				
Other	Trade Secret	PCB	0.51	3.06	5147					
Bisphenol A	80-05-7	PCB	0.01	0.08	132	185.52	(mg) Total	PCB	% of Total Weight	31.23
Glass, oxide	65997-17-3	PCB	3.56	21.12	35554		Glass, oxide	65997-17-3	9.49	
Aluminium hydroxide oxide	24623-77-6	PCB	1.72	10.21	17183		Aluminium hydroxide oxide	24623-77-6	4.59	
Bismaleimide-Triazine resin	Trade Secret	PCB	1.20	7.15	12036		Bismaleimide-Triazine resin	Trade Secret	3.21	
Epoxy resin	Trade Secret	PCB	0.81	4.80	8077		Epoxy resin	Trade Secret	2.16	
Other substances	Trade Secret	PCB	0.62	3.67	6176		Other	Trade Secret	1.65	
Bisphenol A	80-05-7	PCB	0.02	0.09	158		Bisphenol A	80-05-7	0.04	
Cured Resin	Trade Secret	PCB	1.64	9.75	16407		Glass, oxide	65997-17-3	11.38	
Phthalocyanine blue	147-14-8	PCB	0.01	0.03	53		Aluminium hydroxide oxide	24623-77-6	5.50	
Organic pigment	Trade Secret	PCB	0.00	0.02	27		Bismaleimide-Triazine resin	Trade Secret	3.85	
Silica	7631-86-9	PCB	0.02	0.14	240		Epoxy resin	Trade Secret	2.59	
Barium sulfate	7727-43-7	PCB	0.83	4.92	8284		Other substances	Trade Secret	1.98	
Talc	14807-96-6	PCB	0.10	0.57	959		Bisphenol A	80-05-7	0.05	
Organic filler	Trade Secret	PCB	0.03	0.19	320		Cured Resin	Trade Secret	5.25	
Antifoamer and Leveling agent	Trade Secret	PCB	0.03	0.21	346		Phthalocyanine blue	147-14-8	0.02	
Copper	7440-50-8	PCB	13.26	78.78	132618		Organic pigment	Trade Secret	0.01	
Nickel	7440-02-0	PCB	0.65	3.84	6468		Silica	7631-86-9	0.08	
Gold	7440-57-5	PCB	0.14	0.83	1402		Barium sulfate	7727-43-7	2.65	
Silver	7440-22-4	Die attach	0.12	0.70	1170		Talc	14807-96-6	0.31	
Tetramethylene dimethacrylate	2082-81-7	Die attach	0.01	0.05	82		Organic filler	Trade Secret	0.10	
Acrylic Esters	Trade Secret	Die attach	0.00	0.00	6		Antifoamer and Leveling agent	Trade Secret	0.11	
Copper	7440-50-8	Wire	0.35	2.09	3512		Copper	7440-50-8	42.47	
Palladium	7440-05-3	Wire	0.01	0.04	75		Nickel	7440-02-0	2.07	
Silver	7440-22-4	Wire	0.00	0.00	0		Gold	7440-57-5	0.45	
Other	Trade Secret	Wire	0.00	0.00	1		Total 100.00			
Tin	7440-31-5	Solder ball	21.39	127.07	213895					
Silver	7440-22-4	Solder ball	0.22	1.29	2172	0.75	(mg) Total	Die Attach	% of Total Weight	0.13
Copper	7440-50-8	Solder ball	0.11	0.65	1086		Silver	7440-22-4	93.00	
594.06 mg Total Mass			TOTALS:	100.00	594.06	1,000,000				
							Tetramethylene dimethacrylate 6.50			
							Acrylic Esters 0.50			
							Total 100.00			
						2.13	(mg) Total	Wire	% of Total Weight	0.36
							Copper	7440-50-8	97.87	
							Palladium	7440-05-3	2.10	
							Silver	7440-22-4	0.01	
							Other	Trade Secret	0.02	
							Total 100.00			
						129.00	(mg) Total	Solder ball	% of Total Weight	21.72
							Tin	7440-31-5	98.50	
							Silver	7440-22-4	1.00	
							Copper	7440-50-8	0.50	
						594.06	Total	100.00		100.00

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